

VERSION WITH MARKINGS TO SHOW CHANGES MADE**In the claims:**

Please cancel claims 34-40, without prejudice or disclaimer.

Please amend claims 1, 4, 8, 12, 15, 23, 26 and 30 as follows:

1. (Twice Amended) An electronic device comprising:
 - a semiconductor chip including an integrated circuit having at least one electrostatic discharge sensitive device; and
 - a non-semiconductor chip having a substrate formed of an electrically insulating material, positioned in close proximity to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge protection device formed on said substrate, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.

4. (Twice Amended) An electronic device comprising:
 - a semiconductor chip including an integrated circuit; and
 - a non-semiconductor chip having a substrate formed of an electrically insulating material, positioned in close proximity to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge sensitive device formed on said substrate and at least one electrostatic discharge protection device, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.

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8. (Twice Amended) An electronic device comprising:

a semiconductor chip including an integrated circuit having at least one first electrostatic discharge sensitive device; and

a non-semiconductor chip having a substrate formed of an electrically insulating material, positioned in close proximity to said semiconductor chip, said non-semiconductor chip having at least one second electrostatic discharge sensitive device and at least one first electrostatic discharge protection device and at least one second electrostatic discharge protection device formed on said substrate, said first electrostatic discharge protection device electrically connected to said first electrostatic discharge sensitive device and said second electrostatic discharge protection device electrically connected to said second electrostatic discharge sensitive device.

12. (Twice Amended) An electronic device comprising:

a dual chip stack comprising:

a semiconductor chip including an integrated circuit having at least one electrostatic discharge sensitive device; and

a non-semiconductor chip having a substrate formed of an electrically insulating material, attached to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge protection device formed on said substrate, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.

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15. (Twice Amended) An electronic device comprising:

a dual chip stack comprising:

a semiconductor chip including an integrated circuit; and

a non-semiconductor chip having a substrate formed of an electrically insulating material, attached to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge sensitive device and at least one electrostatic discharge protection device formed on said substrate, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.

23. (Twice Amended) An electronic device comprising:

a dual chip stack mounted on a module, said dual chip stack comprising:

a semiconductor chip including an integrated circuit having at least one electrostatic discharge sensitive device; and

a non-semiconductor chip having a substrate formed of an electrically insulating material, attached to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge protection device formed on said substrate, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.

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26. (Twice Amended) An electronic device comprising:
- a dual chip stack mounted on a module, said dual chip stack comprising:
 - a semiconductor chip including an integrated circuit; and
 - a non-semiconductor chip having a substrate formed of an electrically insulating material, attached to said semiconductor chip, said non-semiconductor chip having at least one electrostatic discharge sensitive device and at least one electrostatic discharge protection device formed on said substrate, said electrostatic discharge protection device electrically connected to said electrostatic discharge sensitive device.
30. (Twice Amended) An electronic device comprising:
- a dual chip stack mounted on a module, said dual chip stack comprising:
 - a semiconductor chip including an integrated circuit having at least one first electrostatic discharge sensitive device; and
 - a non-semiconductor chip having a substrate formed of an electrically insulating material, positioned in close proximity to said semiconductor chip, said non-semiconductor chip having at least one second electrostatic discharge sensitive device and at least one first electrostatic discharge protection device and at least one second electrostatic discharge protection device formed on said substrate, said first electrostatic discharge protection device electrically connected to said first electrostatic discharge sensitive device and said second electrostatic discharge protection device electrically connected to said second electrostatic discharge sensitive device.

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